



# **Performance of Rad-Hard Quad Receivers at Extreme Temperatures**

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## Purpose



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### Performance of Rad-Hard Quad Receivers at Extreme Temperatures

- **Characterize the electrical performance and reliabilities as potential space electronic parts under extreme low and high temperature (-125 ~ +150°C) environments extending nominal device specifications (-55 ~ +125°C).**
- **Identify needed enabling technologies to improve operation, reliability, and lifetime of future space missions such as Mars.**



## Presentation outline



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### Performance of Rad-Hard Quad Receivers at Extreme Temperatures

- **Purpose**
- **Rad-Hard Quad Receivers**
- **Test Method**
- **Results**
- **Conclusions**
- **Recommendations**



# Rad-Hard Quad Receiver

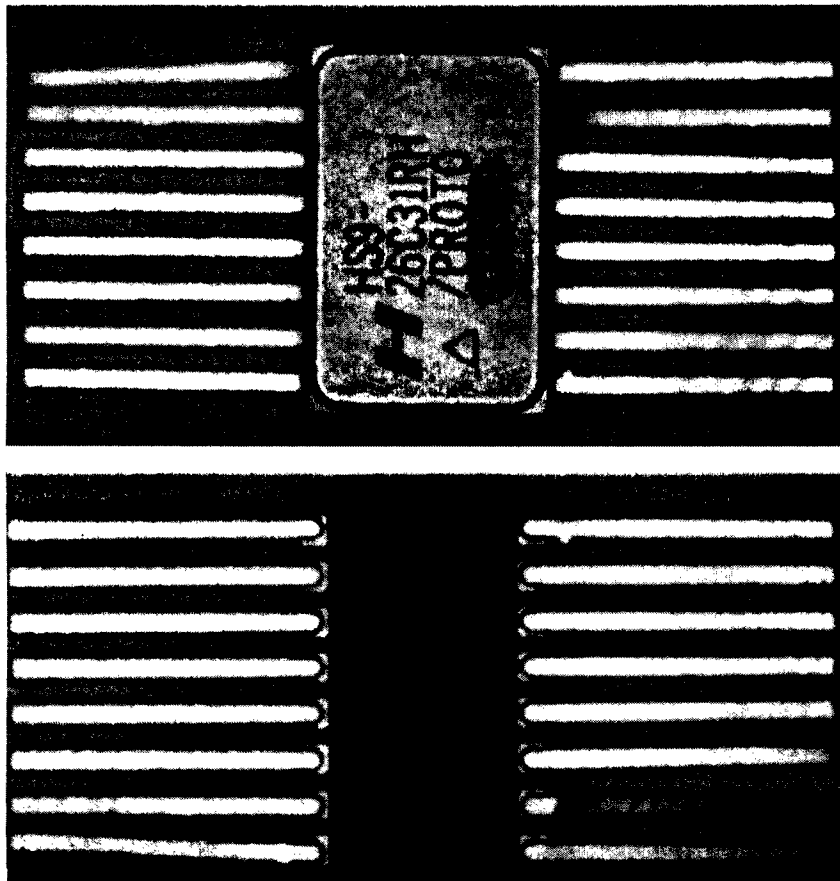


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## Performance of Rad-Hard Quad Receivers at Extreme Temperatures

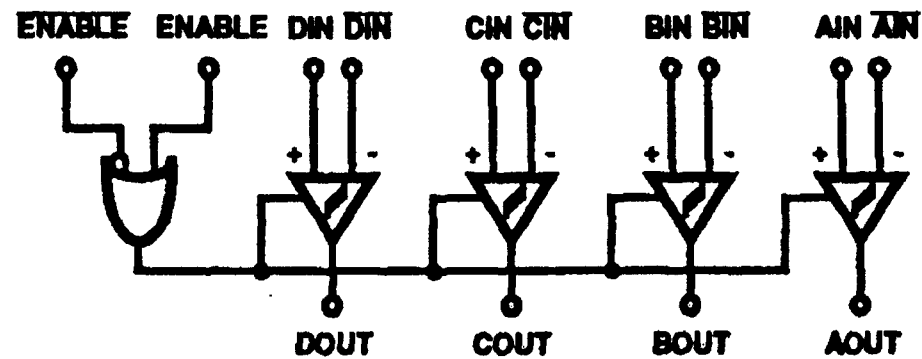
- A quad differential line receiver designed for digital data transmission over balanced lines and meets the requirements of RS-422
- Radiation Hardened CMOS processing for low power consumption, high speed, and reliable operation in the most severe radiation environments.
  - Total Dose: 300KRAD (Si)
  - Single Event Upset (SEU)
  - Single Event Latch-up (SEL)
  - Thresholds:  $>80 \text{ MEV/mg/cm}^2$
- Supply current at low and high state
- Dynamic supply current
- Input current at high and low state
- Output high and low voltages
- Tri-state low and high current
- Propagation delays and transition times.

## Rad-Hard Quad Receivers



- Radiation hardened RS-422 line receiver
- Has CMOS enable pin input levels and accepts TTL-level enable signals
- The two circuits are identical except for the configuration of the logic input buffers
- The HS-26C32RH has the same input characteristics (impedance, hysteresis, failsafe) as commercial types.

# Functional Diagram



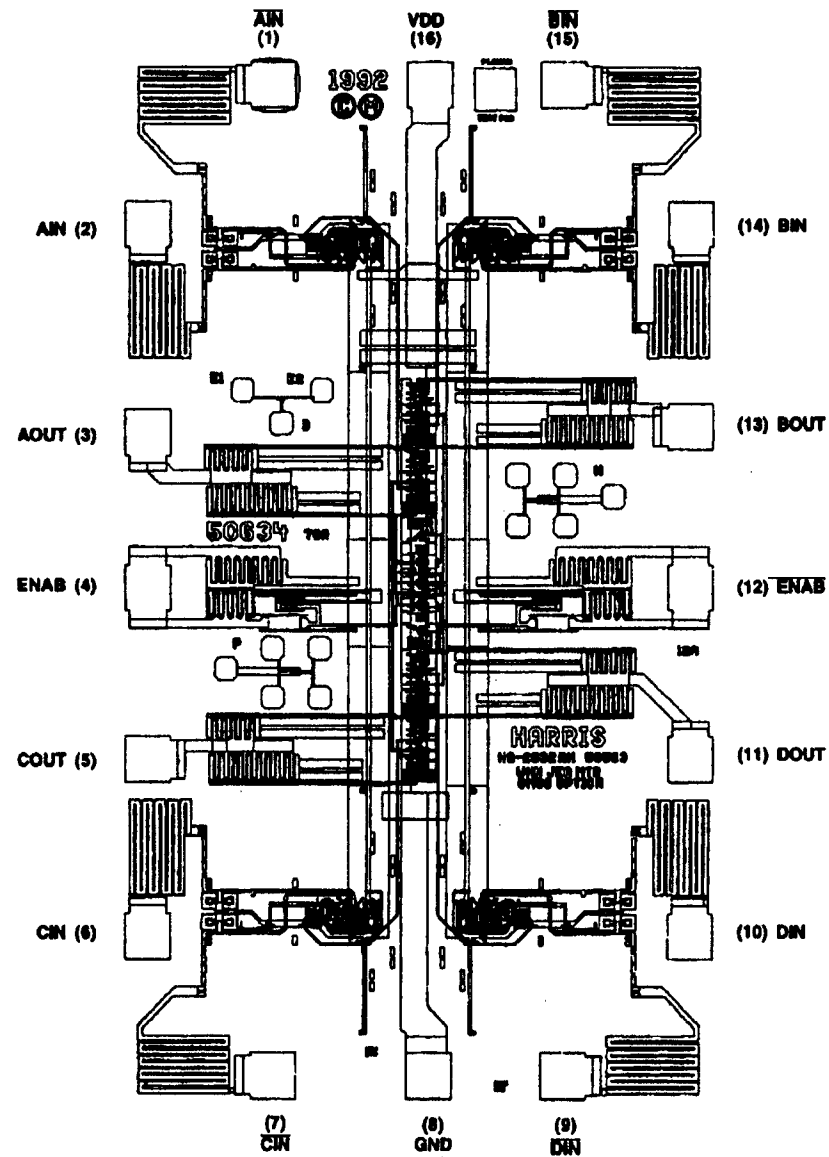
TRUTH TABLE

DEVICE POWER ON/OFF	INPUTS			OUTPUT
	ENABLE	ENABLE	INPUT	OUT
ON	0	1	X	HI-Z
ON	1	X	$VID \geq VTH (Max)$	1
ON	1	X	$VID \leq VTH (Min)$	0
ON	X	0	$VID \geq VTH (Max)$	1
ON	X	0	$VID \leq VTH (Min)$	0
ON	1	X	Open	1
ON	X	0	Open	1

## Die Characteristics

- **Die Dimensions:**  $2140\mu\text{m} \times 3290\mu\text{m} \times 533\mu\text{m} \pm 25.4\mu\text{m}$
- **Backside Finish:** Silicon
- **Passivation:**
  - **Type:**  $\text{SiO}_2$
  - **Thickness:**  $800\text{nm} \pm 100\text{nm}$
- **Metallization:**
  - **M1:** Mo / TiW
  - **Thickness:** 580nm
  - **Thickness:**  $1000\text{nm} \pm 100\text{nm}$
- **Substrate Potential:** Internally connected to  $V_{DD}$
- **Worst Case Current Density:**  $< 2.0\text{E}5 \text{ A/cm}^2$
- **Transistor Count:** 315
- **Process:** Radiation Hardened CMOS, AVLSI

# Die Layout



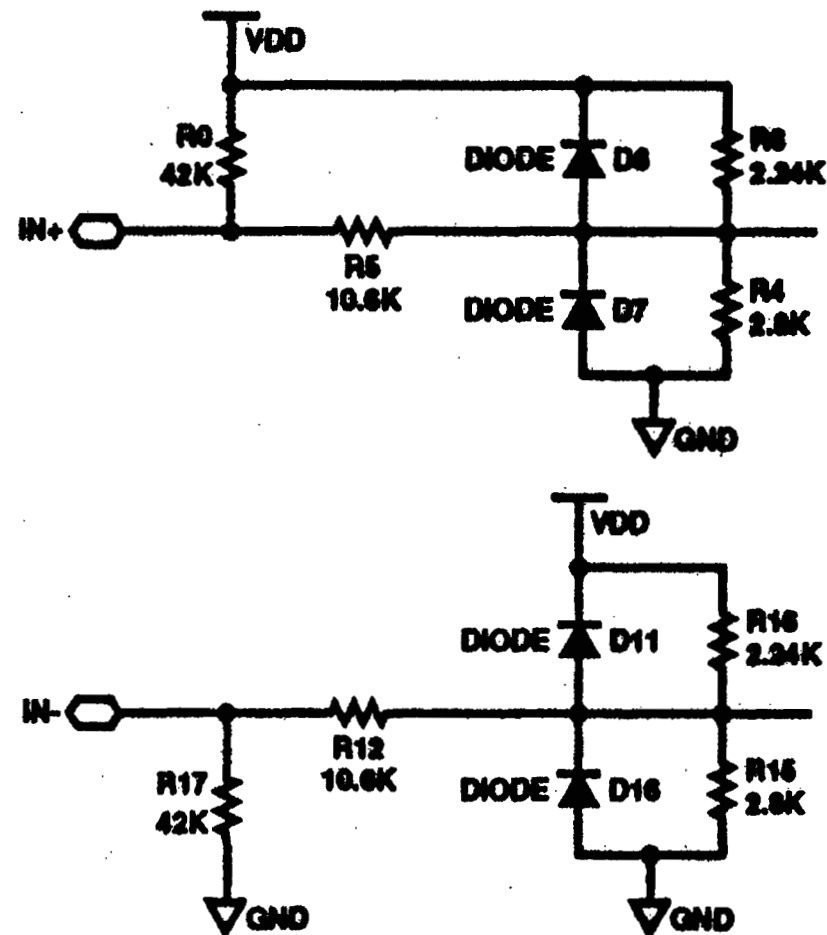




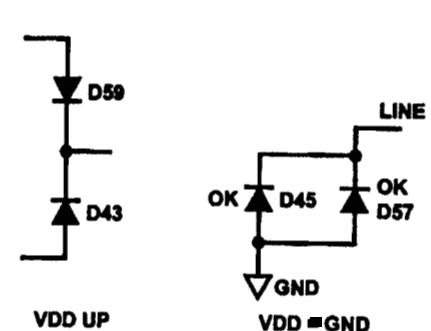
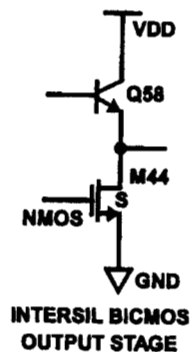
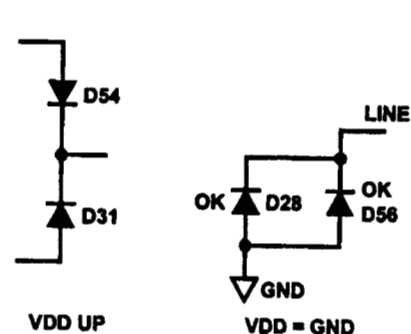
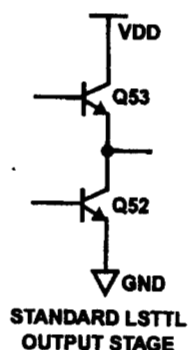
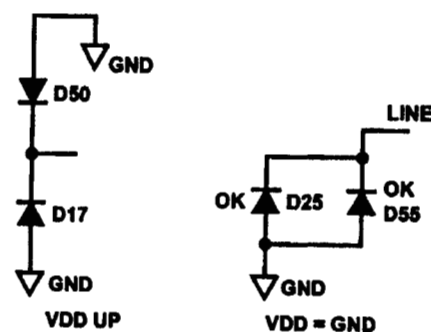
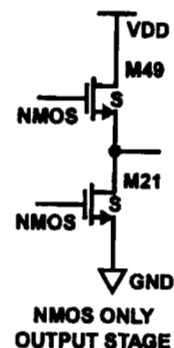
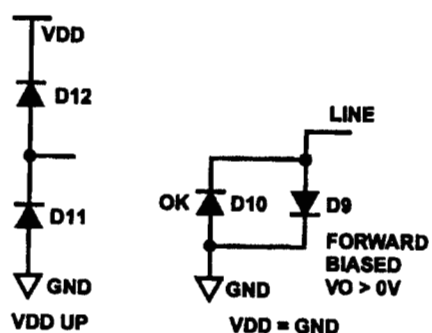
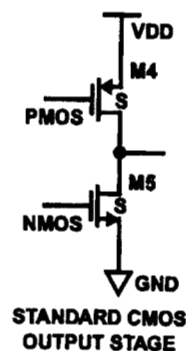
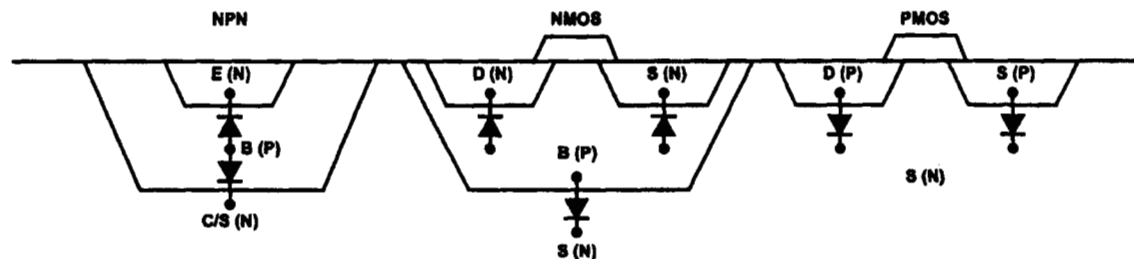
## Schematic of the HS-26C(T)32RH input structure



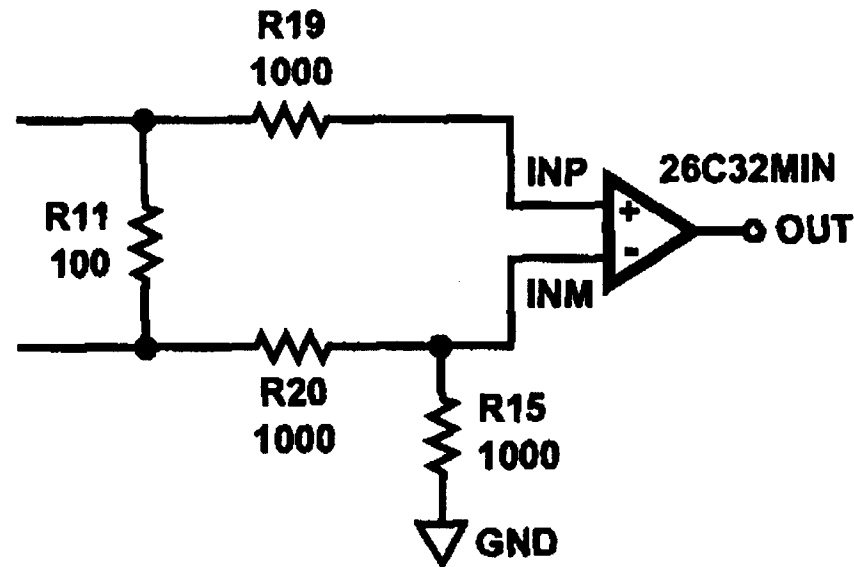
### Performance of Rad-Hard Quad Receivers at Extreme Temperatures



# Parasitic Diodes for Each Output

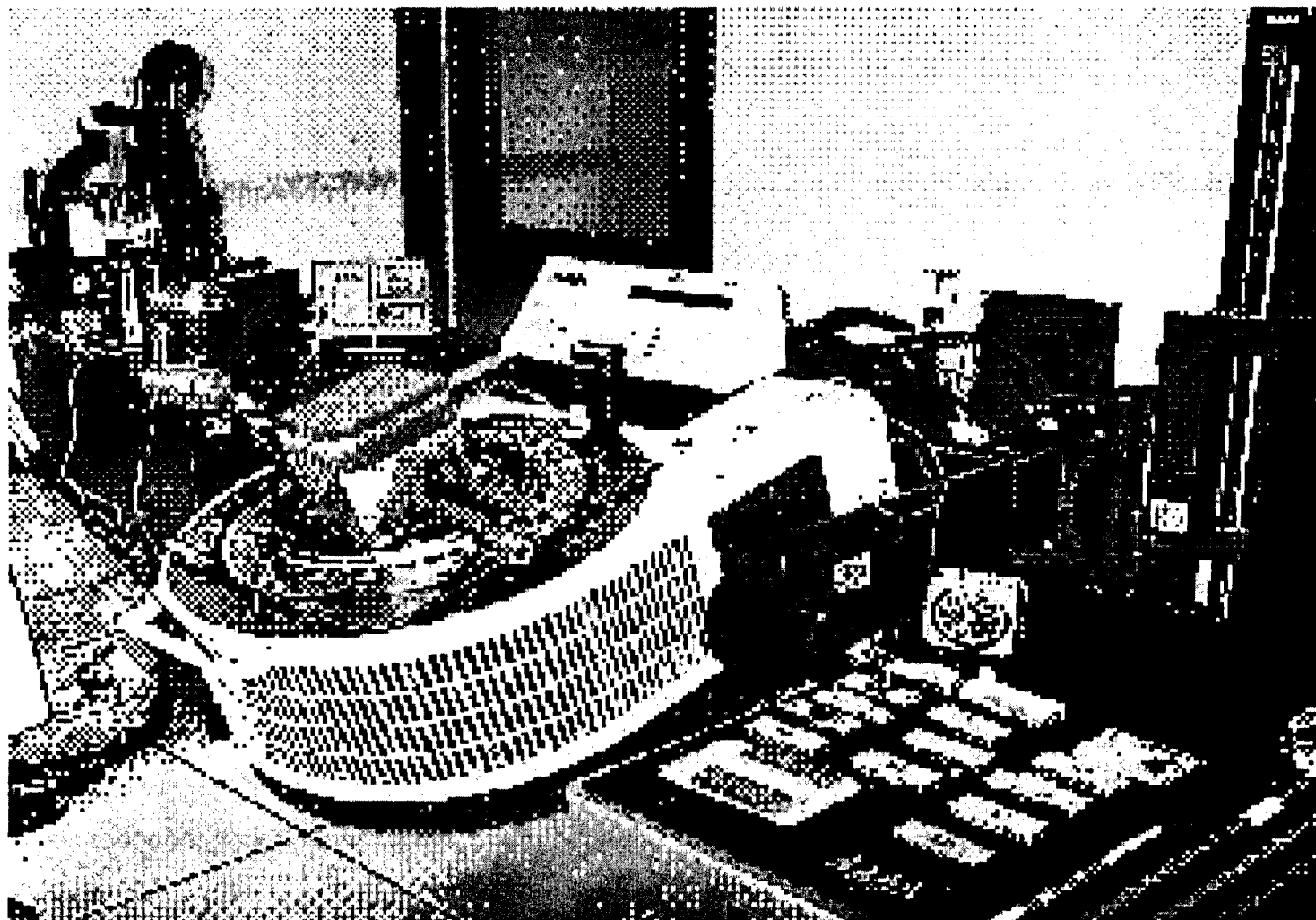


## Adequate input differential voltage for open line fault conditions



- Produces too small an input differential voltage in the open-line fault condition
- The internal input bias network is shunted by the termination resistor
- The internal input bias network is supplemented externally to compensate for the termination resistor

## Performance of Rad-Hard Quad Receivers at Extreme Temperatures

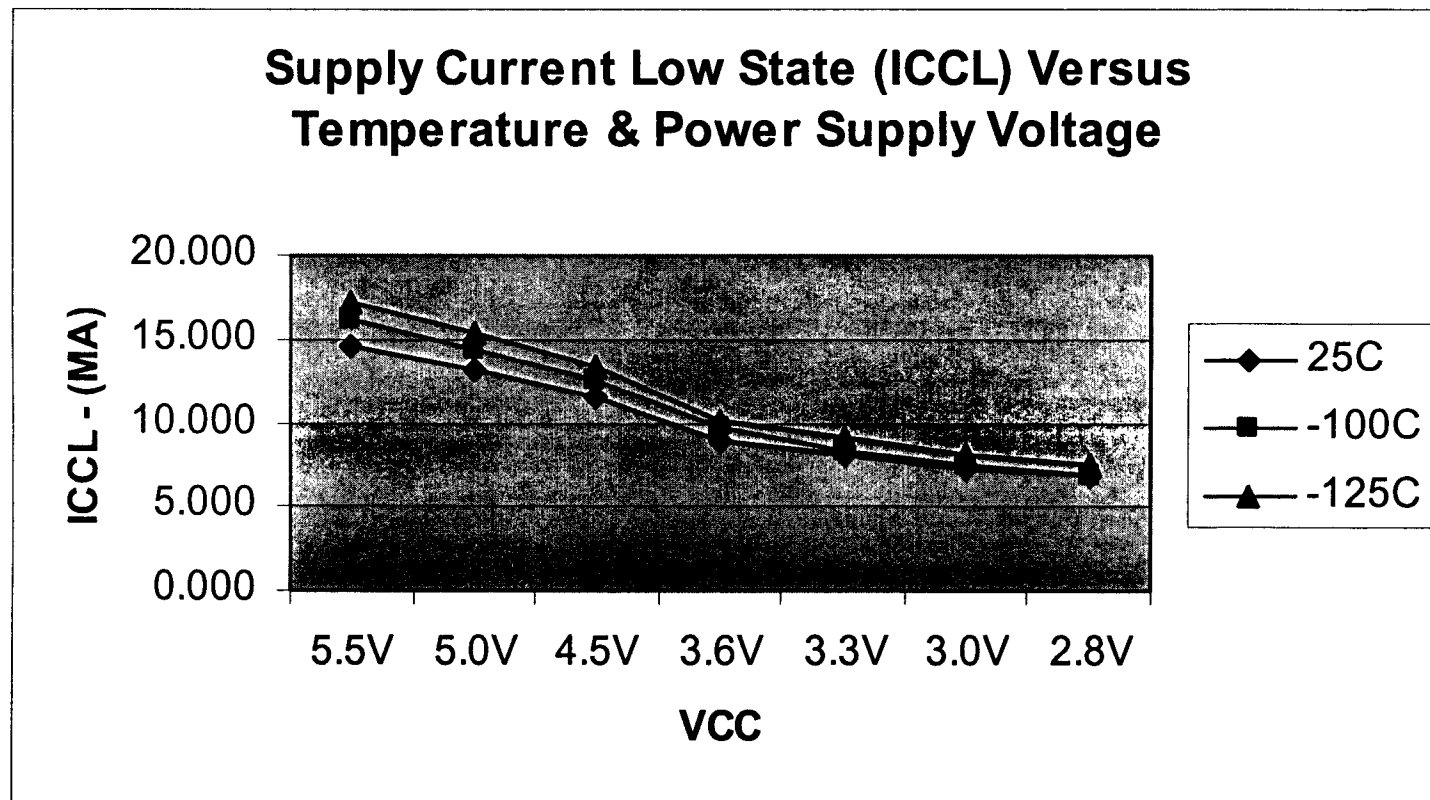




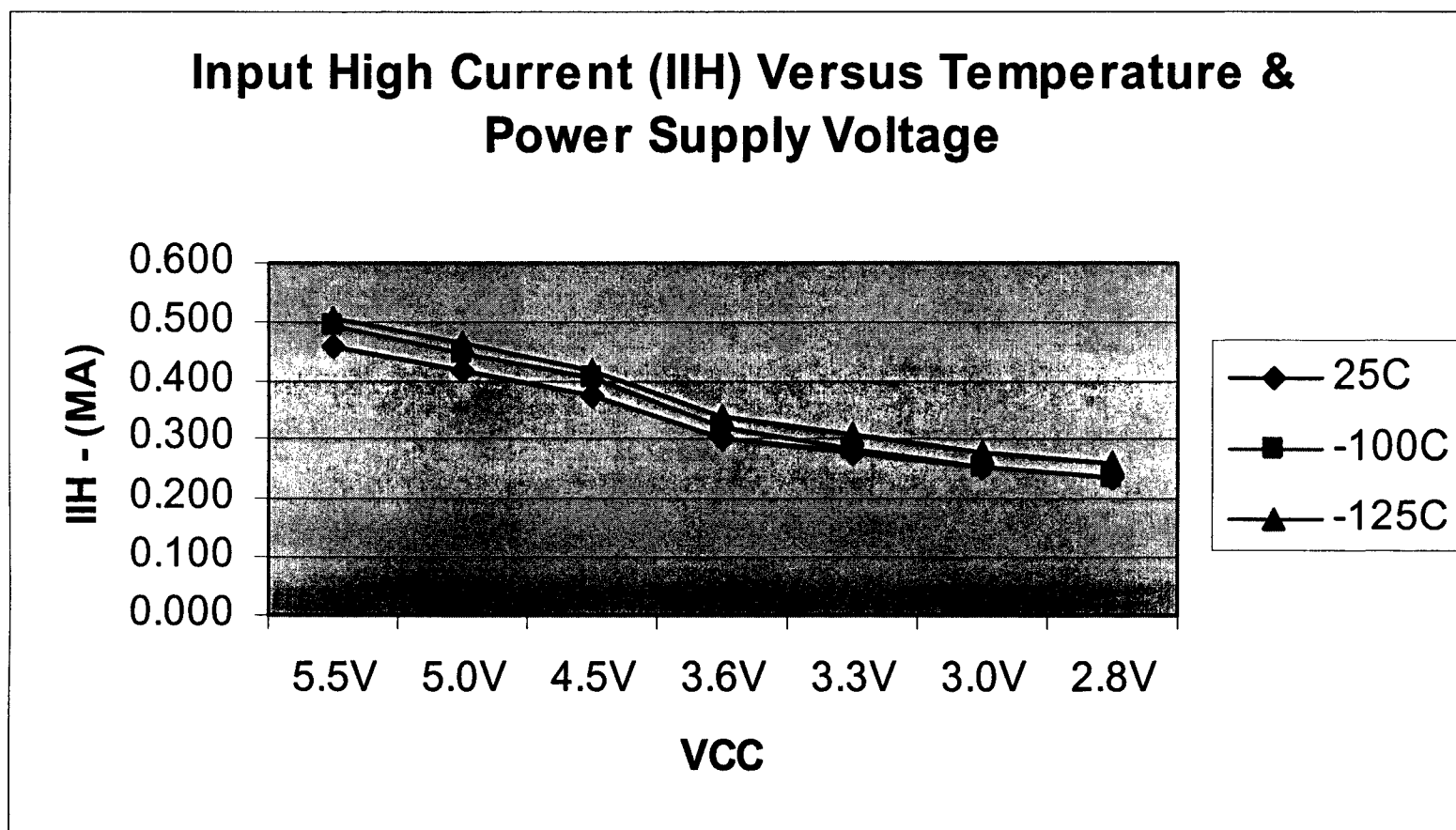
## Characteristics of the quiescent power supply currents



### Performance of Rad-Hard Quad Receivers at Extreme Temperatures



**Performance of Rad-Hard Quad Receivers at Extreme Temperatures**

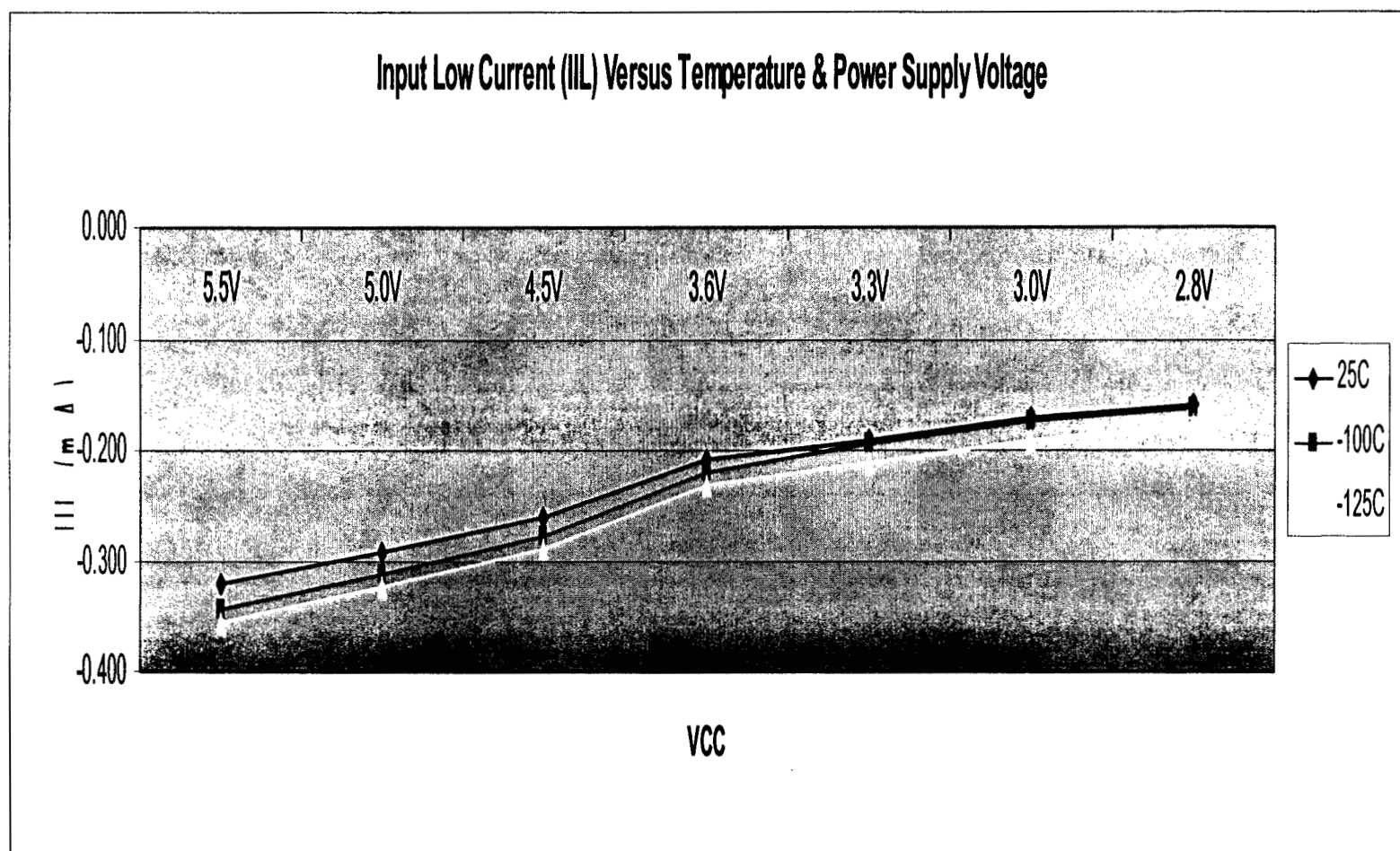




## Characteristics of the input low current



### Performance of Rad-Hard Quad Receivers at Extreme Temperatures

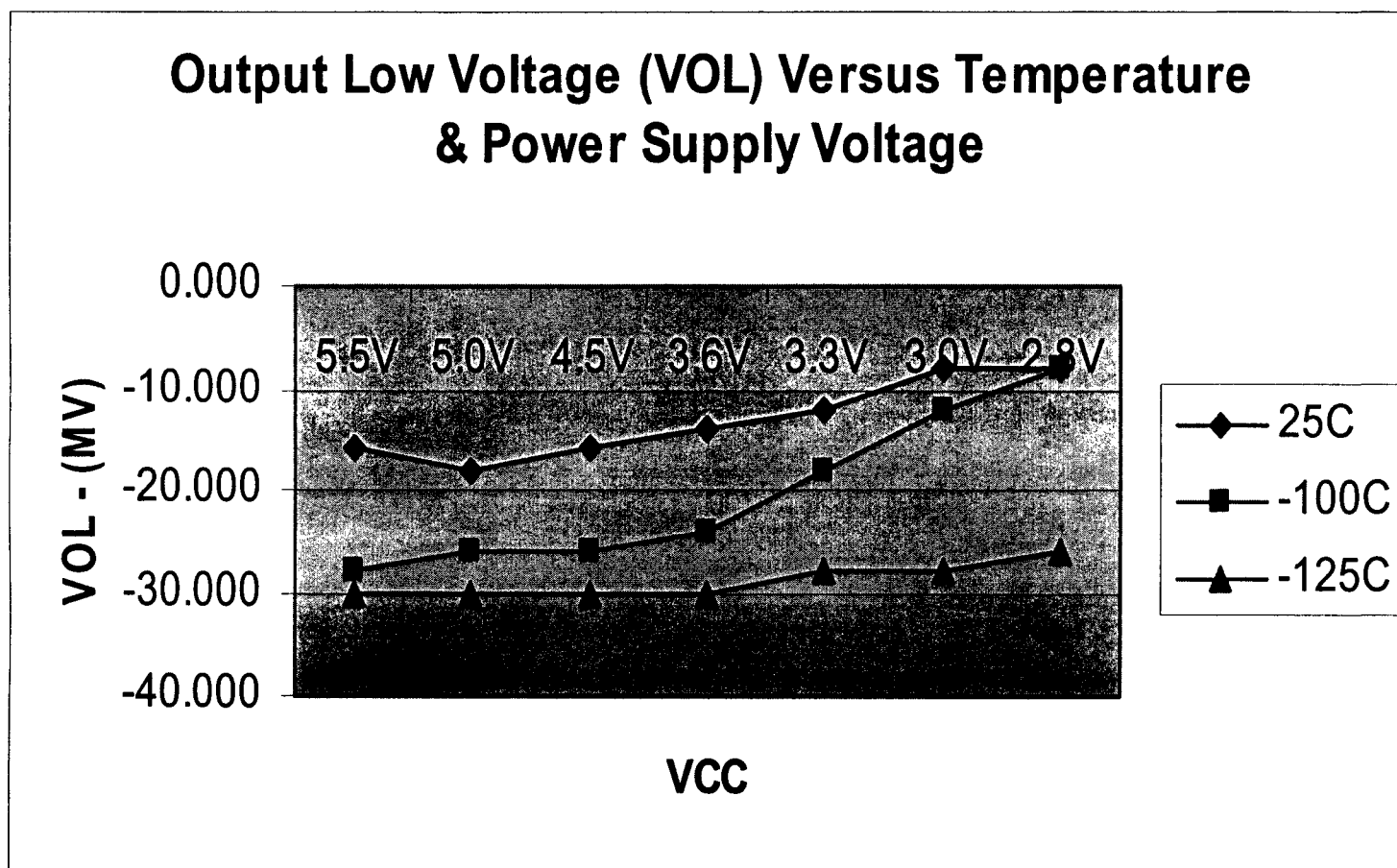




## Characteristics of the output low voltage



### Performance of Rad-Hard Quad Receivers at Extreme Temperatures



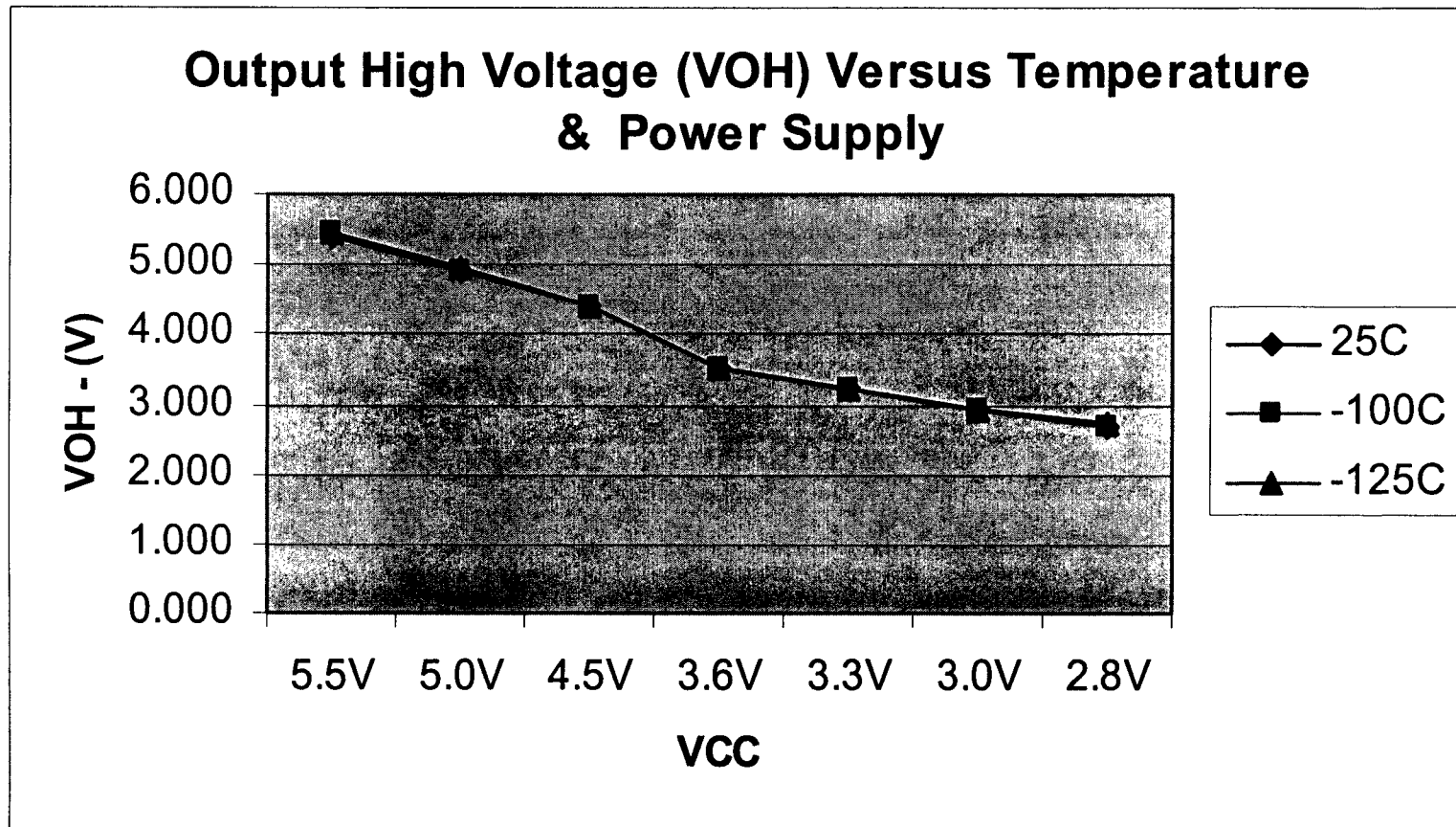




## Characteristics of the output high voltage



### Performance of Rad-Hard Quad Receivers at Extreme Temperatures

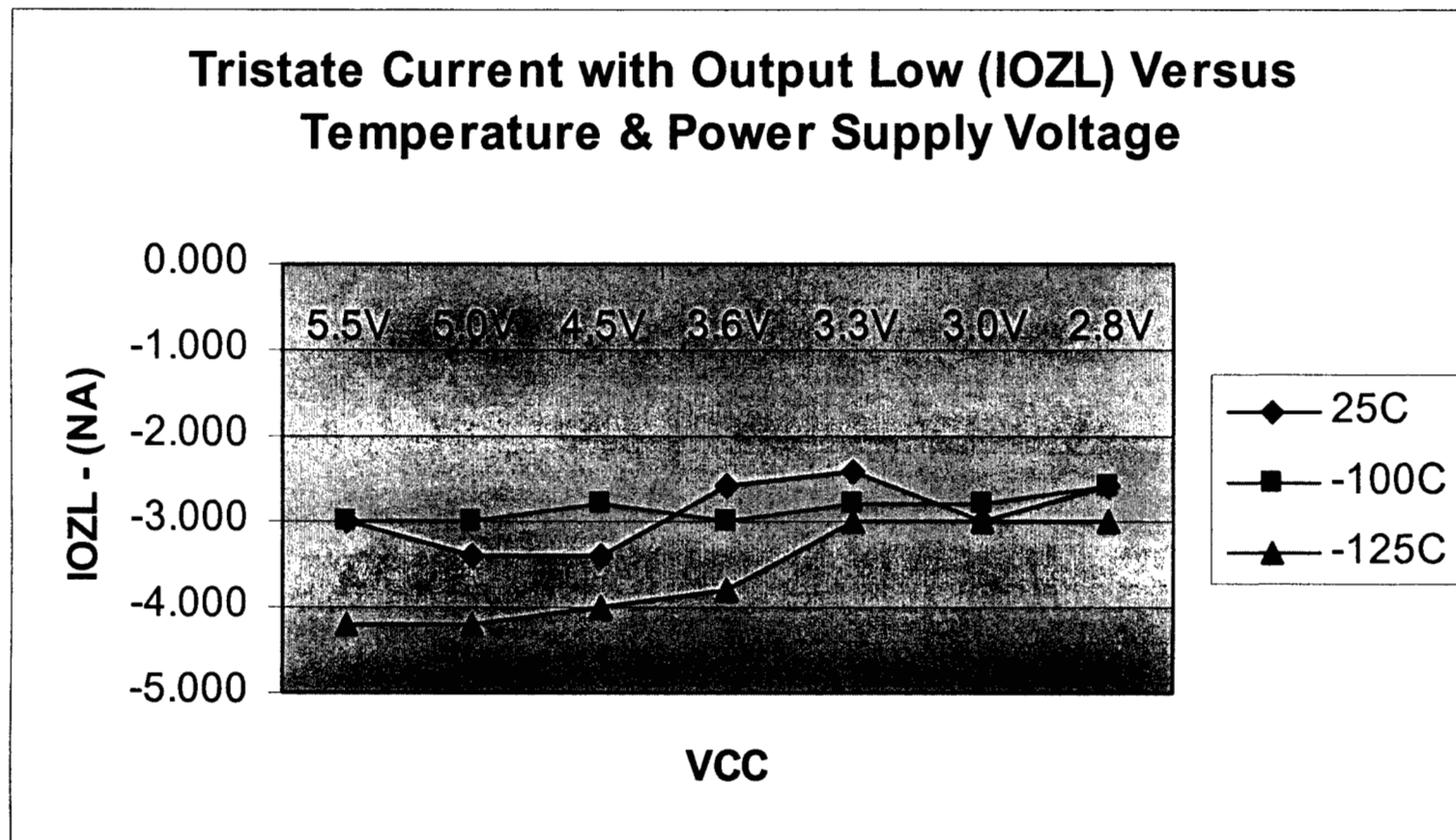




## Characteristics of the tri-state leakage current for output low



### Performance of Rad-Hard Quad Receivers at Extreme Temperatures

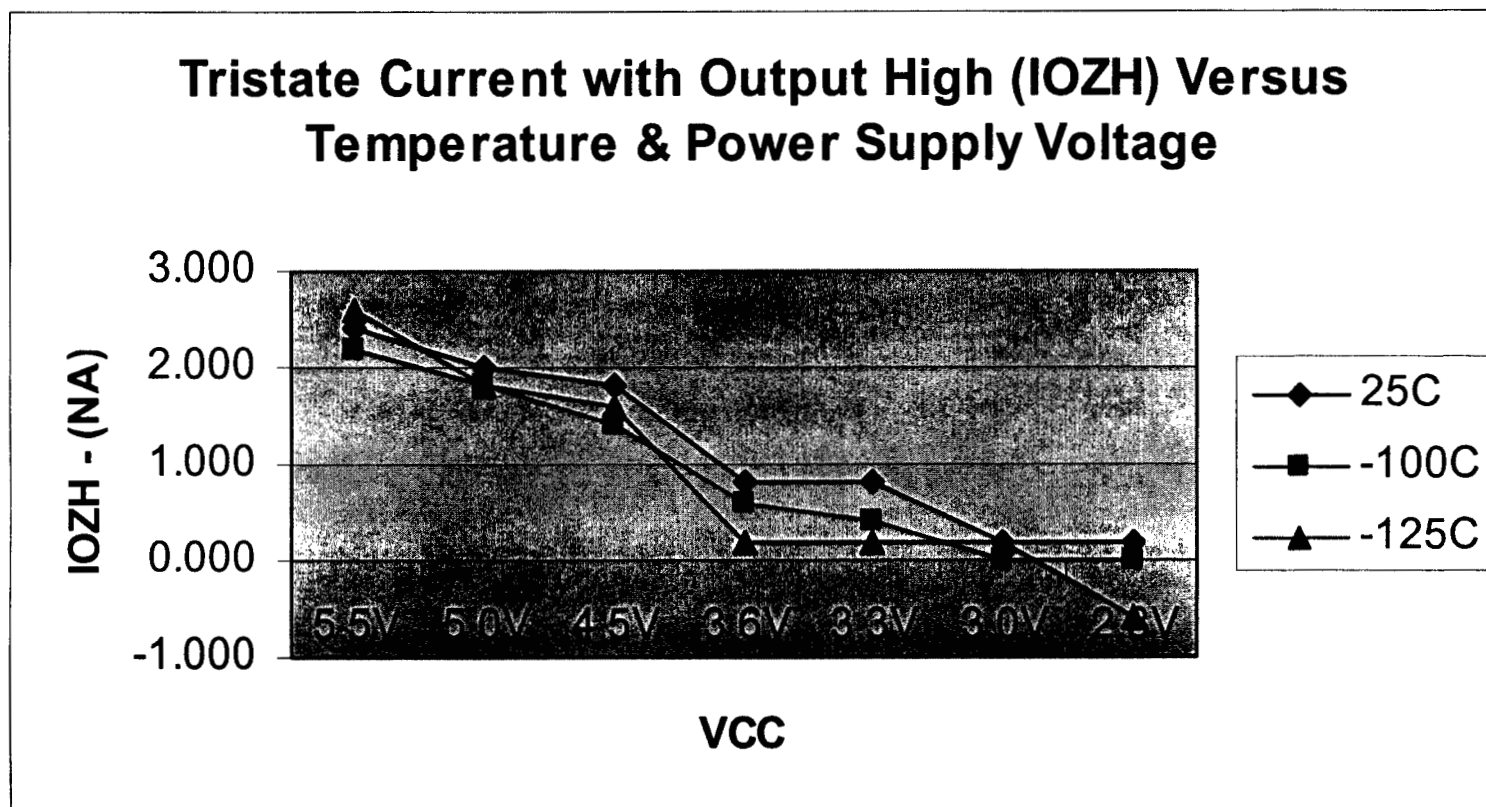




## Characteristics of the tri-state leakage current for output high



### Performance of Rad-Hard Quad Receivers at Extreme Temperatures

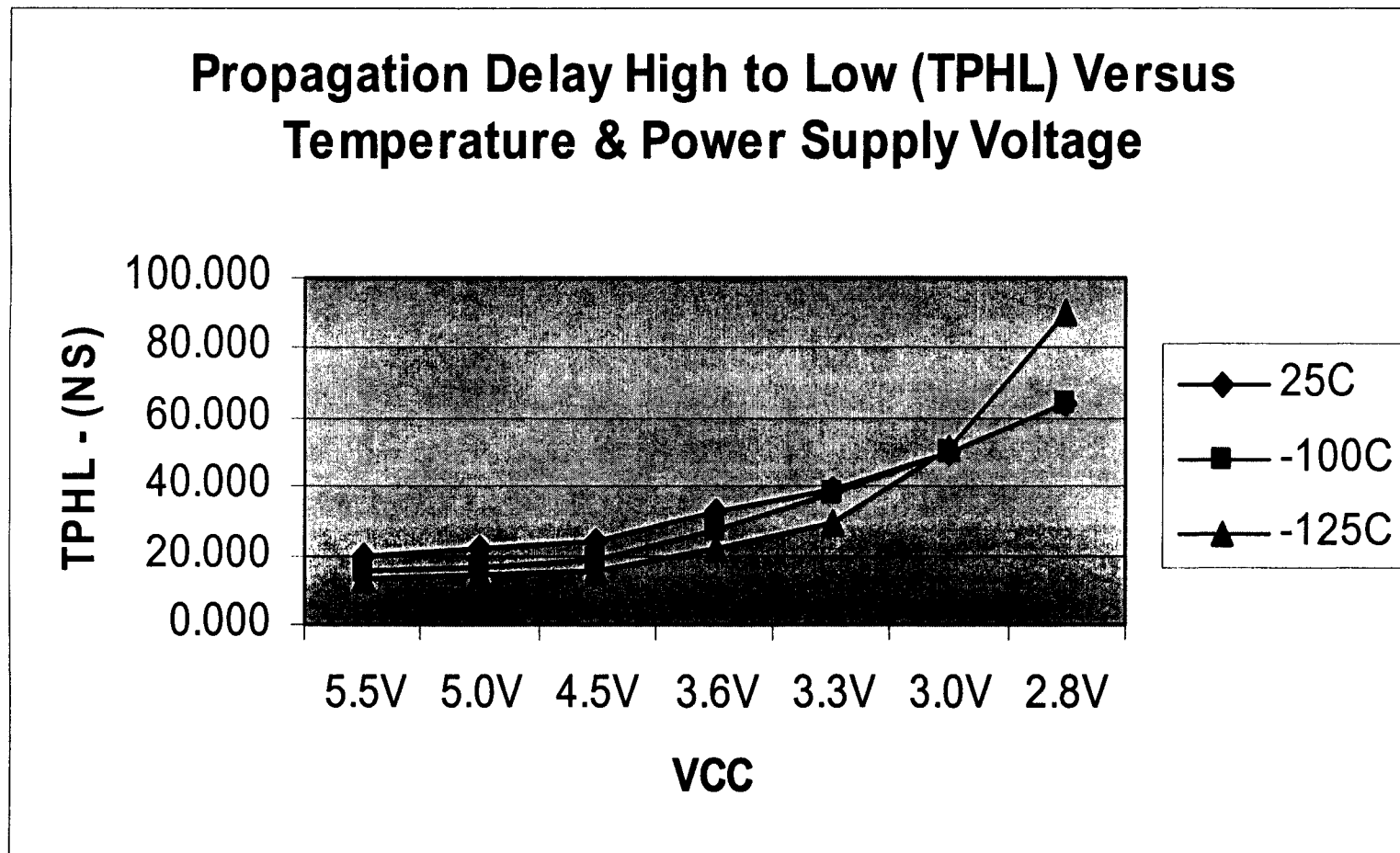




# Characteristics of the propagation delay times from high to low state



## Performance of Rad-Hard Quad Receivers at Extreme Temperatures

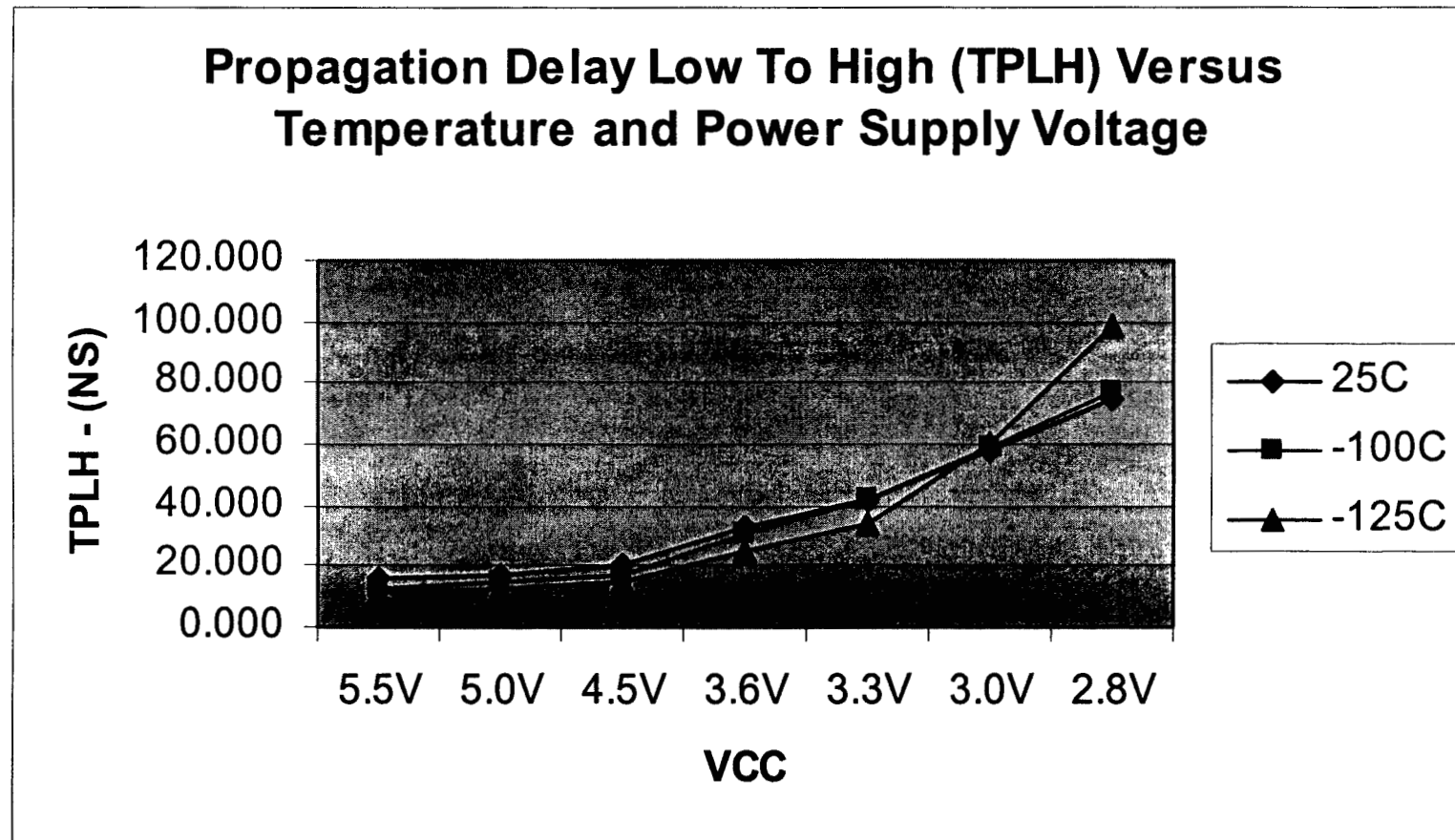




## Characteristics of the propagation delay times from low to high state



### Performance of Rad-Hard Quad Receivers at Extreme Temperatures

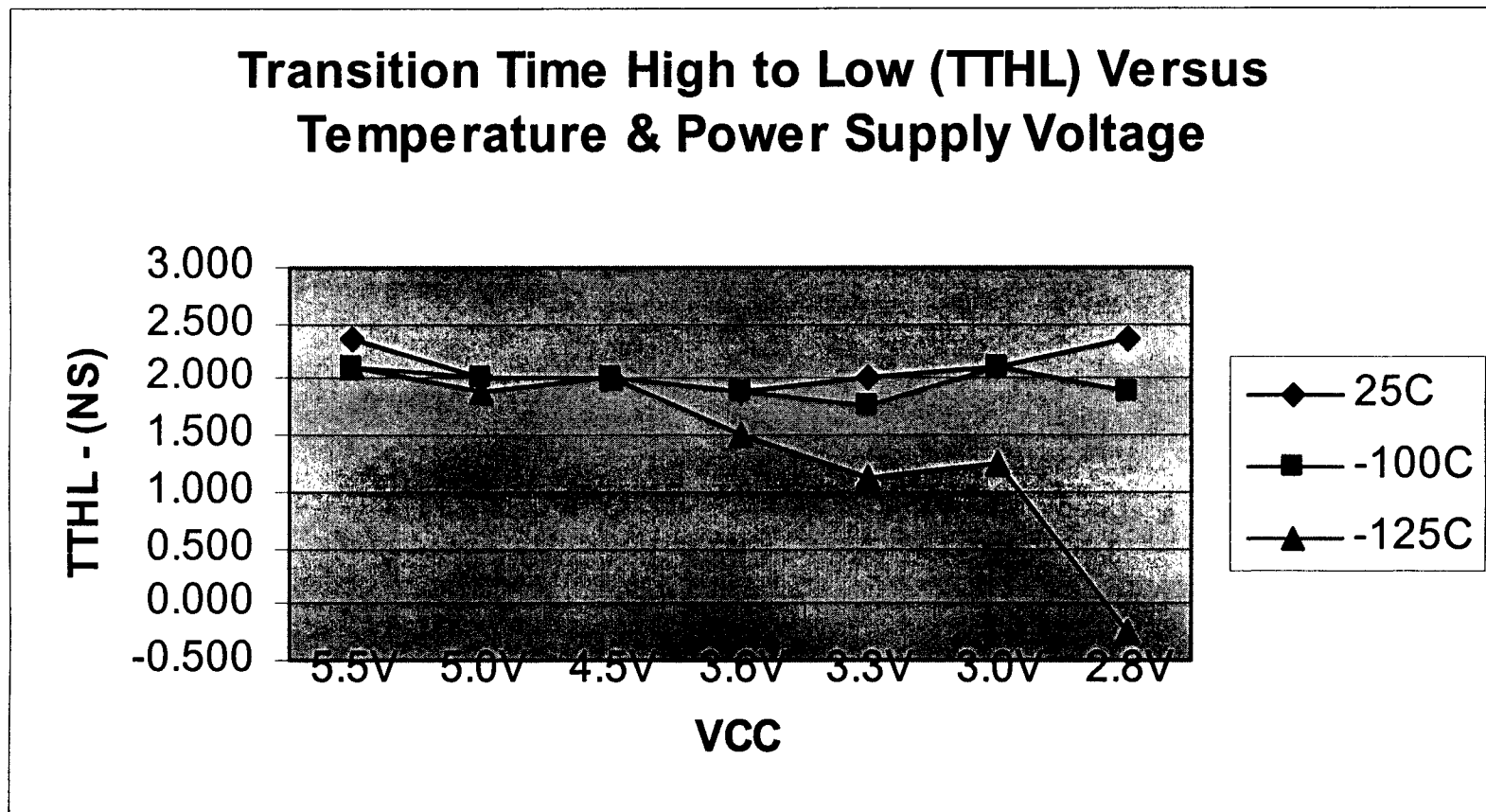




## Characteristics of the transition times from high to low state



### Performance of Rad-Hard Quad Receivers at Extreme Temperatures





## Conclusions



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### Performance of Rad-Hard Quad Receivers at Extreme Temperatures

- **The test results of the basic parameters of a radiation hardened quad receivers at extreme cold environment indicates that the device can be applied for the potential application in Mars exploration missions even at -125 °C**



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### Performance of Rad-Hard Quad Receivers at Extreme Temperatures

- We do not recommend using this part below 3V supply voltage in applications requiring operation down  $-125^{\circ}\text{C}$ .
- The output rise and fall times,  $t_{\text{TLH}}$  and  $t_{\text{THL}}$ , were well within the SMD max limits of 12ns at  $5\text{V} \pm 10\%$  and 15ns at  $3.3\text{V} \pm 10\%$ .
- The parts though exhibited anomalous behavior at the conditions of 2.8V supply voltage and low temperatures.





## Acknowledgements



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